6. (Amended) The tape carrier type semiconductor device according to claim 5, wherein said flexible substrate includes a rib formed substantially perpendicular to the plurality of first slits.

8. (Amended) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate includes a rib formed substantially perpendicular to the first slit.

10. (Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate,

wherein said flexible substrate includes a first slit for folding said flexible substrate and a rib formed substantially perpendicular to the first slit, and

wherein said first slit comprises a first sub-slit and a second sub-slit with a connector therebetween to reduce warpage.

13. (Amended) A flexible substrate, comprising:

a first slit having a connector thereto for connecting both sides ends of the first slit to reduce warpage, and on whose surface wiring having a predetermined pattern is formed,

wherein said first slit comprises a first sub-slit and a second sub-slit with said connector therebetween.

Please add the following new claims:

19. (New) The tape carrier type semiconductor device according to claim 1, wherein said connector comprises a bridge arranged at the center of said first slit.

20. (New) The tape carrier type semiconductor device according to claim 1, wherein said first slit comprises a stress-releasing slit.

21. (New) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises at least one of a polyimide resin film, an organic polymer film, a polyamide resin film, a polyester resin film and a composite film.

22. (New) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a terminal area adjacent said first slit.

23. (New) The tape carrier type semiconductor device according to claim 22, wherein said first slit is situated between said driver circuit and said terminal area, said first slit comprises a rectangular shape with a longitudinal side parallel to said terminal area.

24. (New) The tape carrier type semiconductor device according to claim 1, wherein a warpage of said tape carrier type semiconductor device is no more then approximately 4.8% of a length of said tape carrier type semiconductor device.

25. (New) The tape carrier type semiconductor device according to claim 10, wherein said